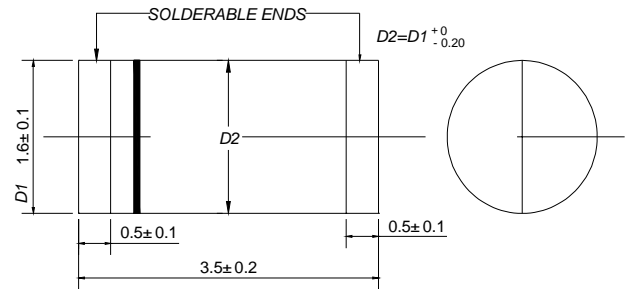




DO - 213AA

Features

- Plastic package has underwriters laboratories flammability classification 94V-0
- Glass passivated chip junction
- For surface mount applications
- High temperature metallurgically bonded construction
- Cavity-free glass passivated junction
- High temperature soldering guaranteed:450 /5 seconds at terminals.Complete device sub-mersible temperature of 265 for 10 seconds in solder bath



Dimensions in millimeters

Mechanical Data

- Case: JEDEC DO-213AA,molded plastic
- Polarity: Color band denotes cathode
- Weight: 0.0014 ounces, 0.036 grams
- Mounting position: Any

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25 ambient temperature unless otherwise specified.

Single phase,half wave,60 Hz,resistive or inductive load. For capacitive load,derate current by 20%.

| | | EGL 341A | EGL 341B | EGL 341D | EGL 341F | EGL 341G | EGL 341H | EGL 341J | UNITS |
|--|------------|----------------|-------------|-------------|-------------|-------------|-------------|-------------|---------|
| Maximum recurrent peak reverse voltage | V_{RRM} | 50 | 100 | 200 | 300 | 400 | 500 | 600 | V |
| Maximum RMS voltage | V_{RMS} | 35 | 70 | 140 | 210 | 280 | 350 | 420 | V |
| Maximum DC blocking voltage | V_{DC} | 50 | 100 | 200 | 300 | 400 | 500 | 600 | V |
| Maximum average forward rectified current $T_T=75$ | $I_{(AV)}$ | 1.0 | | | | | | | A |
| Peak forward surge current 8.3ms single half-sine-wave superimposed on rated load (JEDEC Method) | I_{FSM} | 30 | | | | | | | A |
| Maximum instantaneous forward voltage @1.0A | V_F | 1.25 | | 1.35 | | 1.70 | | V | |
| Maximum reverse current @ $T_A=25$ at rated DC blocking voltage @ $T_A=125$ | I_R | 5.0 50 | | | | | | | μA |
| Maximum reverse recovery time (Note 1) | t_{rr} | 50 | | | | | | | ns |
| Typical junction capacitance (Note 2) | C_j | 15 | | | | | | | pF |
| Typical thermal resistance (Note 3) | R_{0JA} | 150 | | | | | | | K/W |
| Operating junction temperature range | T_j | - 55 ---- +175 | | | | | | | |
| Storage temperature range | T_{STG} | - 55 ---- +175 | | | | | | | |

NOTE: 1. Measured with $I_F=0.5A, I_R=1.0A, I_{rr}=0.25A$

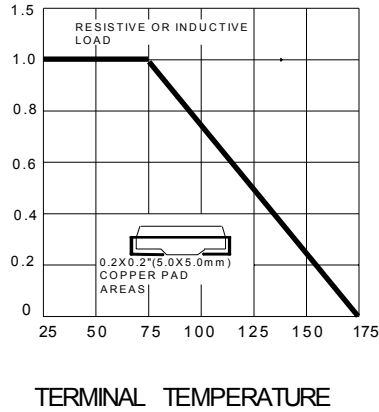
2. Measured at 1.0MHz and applied reverse voltage of 4.0V DC.

3. Thermal resistance from junction to ambient, 0.24×0.24"(6.0×6.0mm) copper pads to each terminal.

Ratings AND Characteristic Curves

FIG.1 – FORWARD CURRENT DERATING CURV

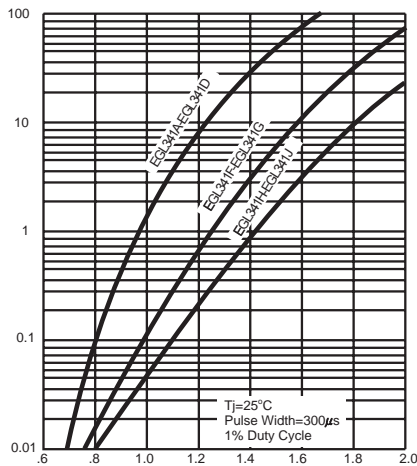
AVERAGE FORWARD RECTIFIED CURRENT, AMPERES



TERMINAL TEMPERATURE

FIG.3 – TYPICAL INSTANTANEOUS FORWARD CHARACTERISTICS

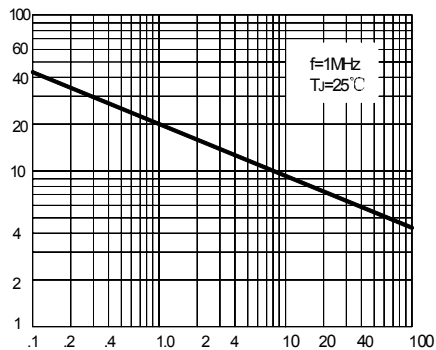
INSTANTANEOUS FORWARD CURRENT, AMPERES



INSTANTANEOUS FORWARD VOLTAGE(V)

FIG.5 – TYPICAL JUNCTION CAPACITANCE

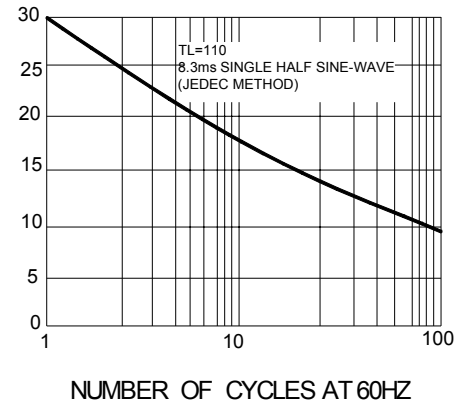
JUNCTION CAPACITANCE(pF)



REVERSE VOLTAGE(V)

FIG.2 – MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT

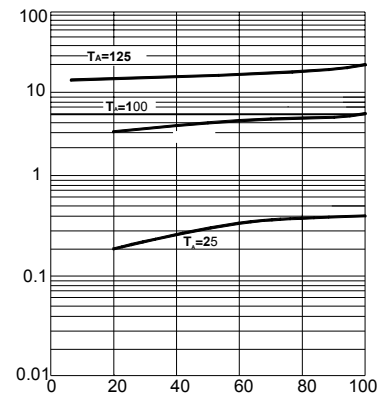
PEAK FORWARD SURGE CURRENT, AMPERES



NUMBER OF CYCLES AT 60HZ

FIG.4 – TYPICAL REVERSE CHARACTERISTICS

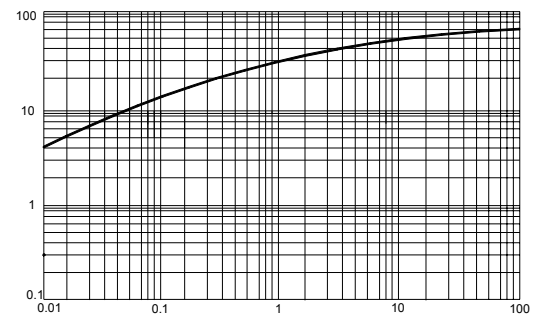
INSTANTANEOUS REVERSE LEAKAGE CURRENT (mA)



PERCENT OF RATED PEAK REVERSE VOLTAGE. (%)

FIG.6 – TYPICAL TRANSIENT THERMAL IMPEDANCE

TRANSIENT THERMAL IMPEDANCE (°C/W)



T,PULSE DURATION,